

Fig. 1

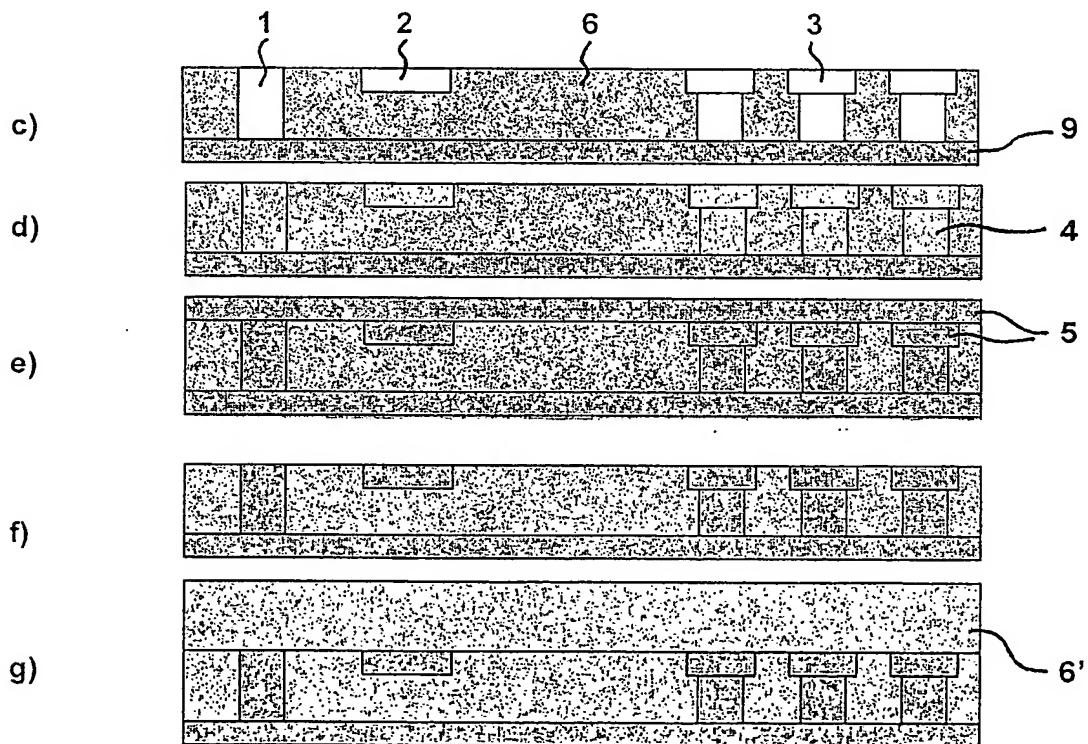


Fig. 2

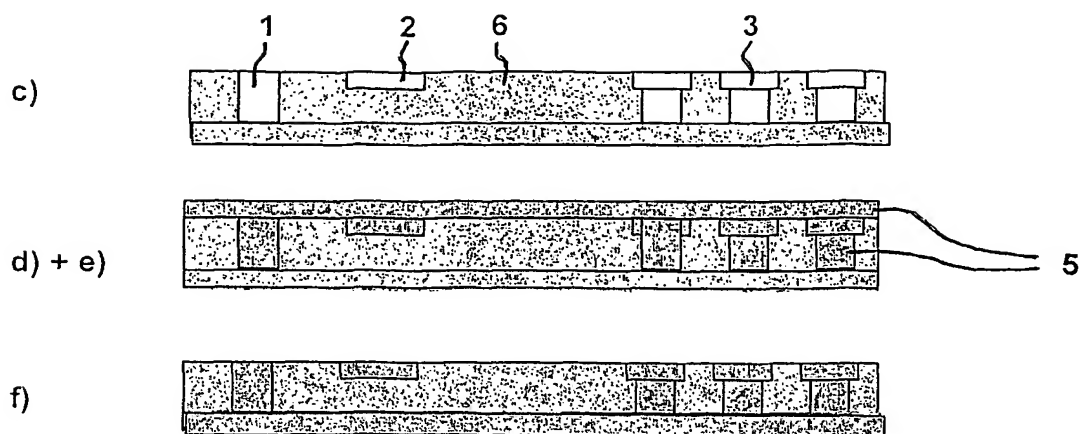


Fig. 3

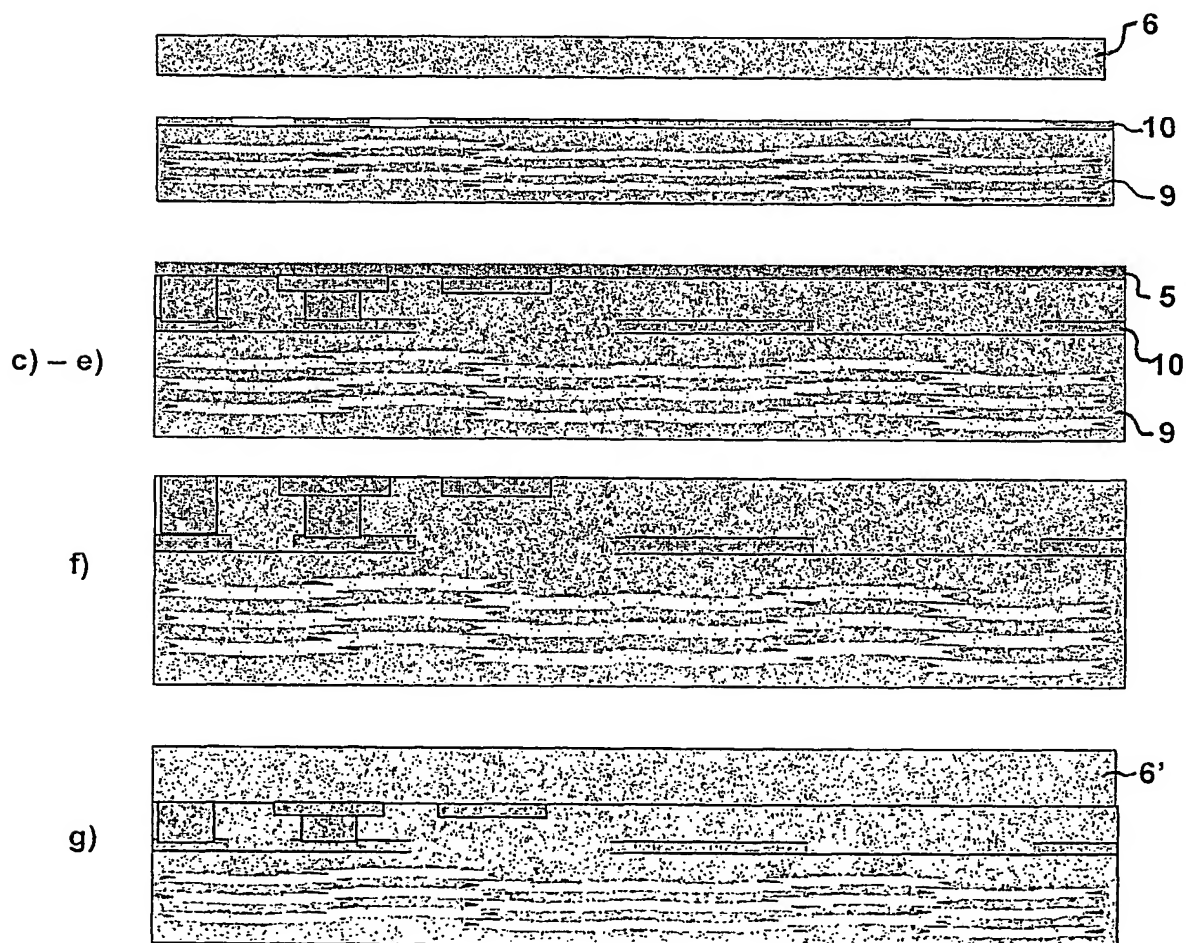


Fig. 4

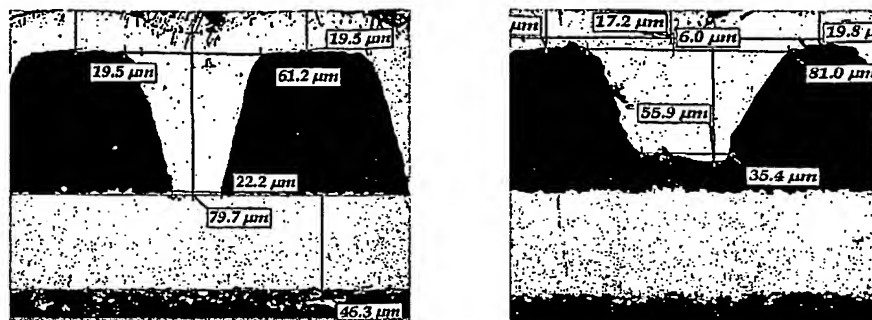


Fig. 5

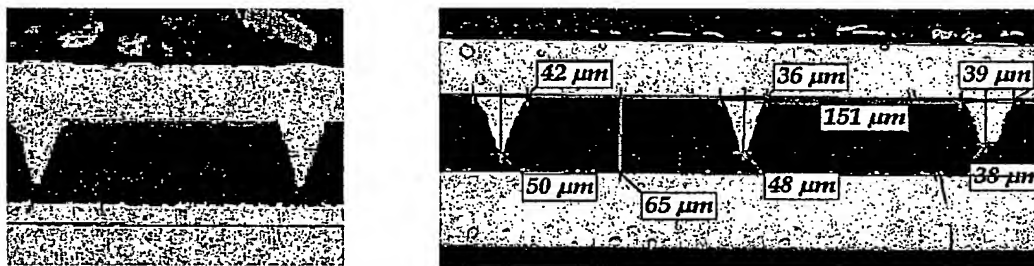


Fig. 6

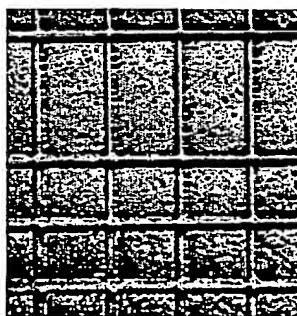


Fig. 7

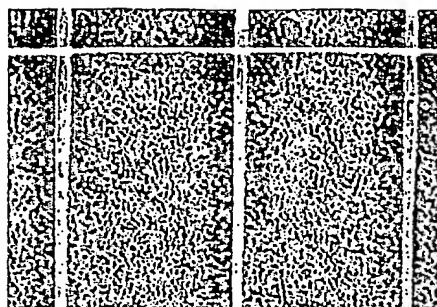


Fig. 8

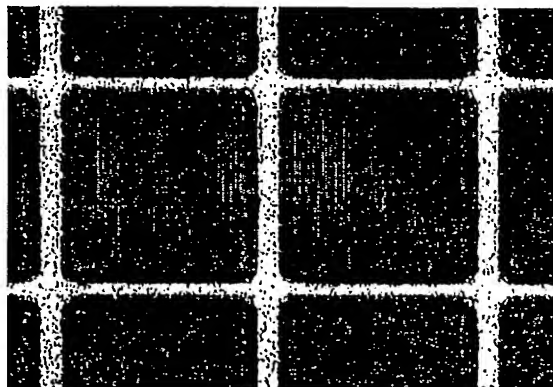
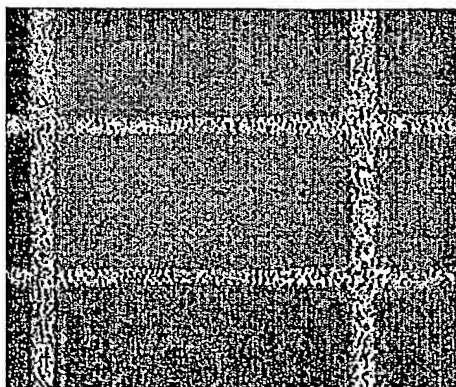


Fig. 9

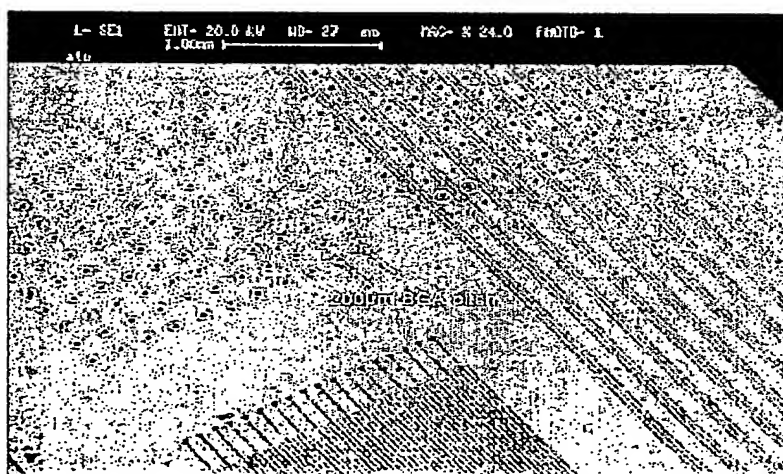


Fig. 10

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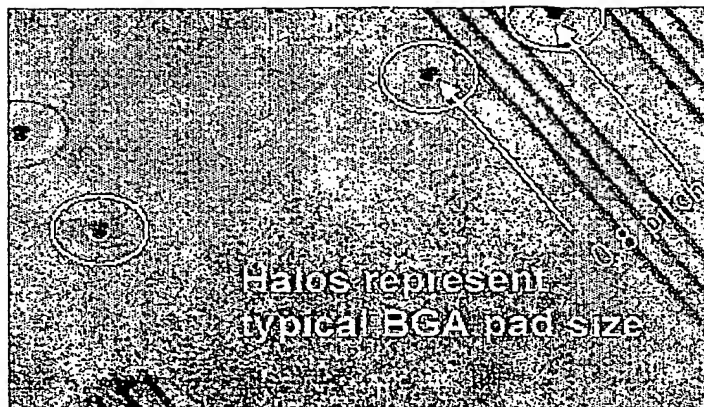


Fig. 11

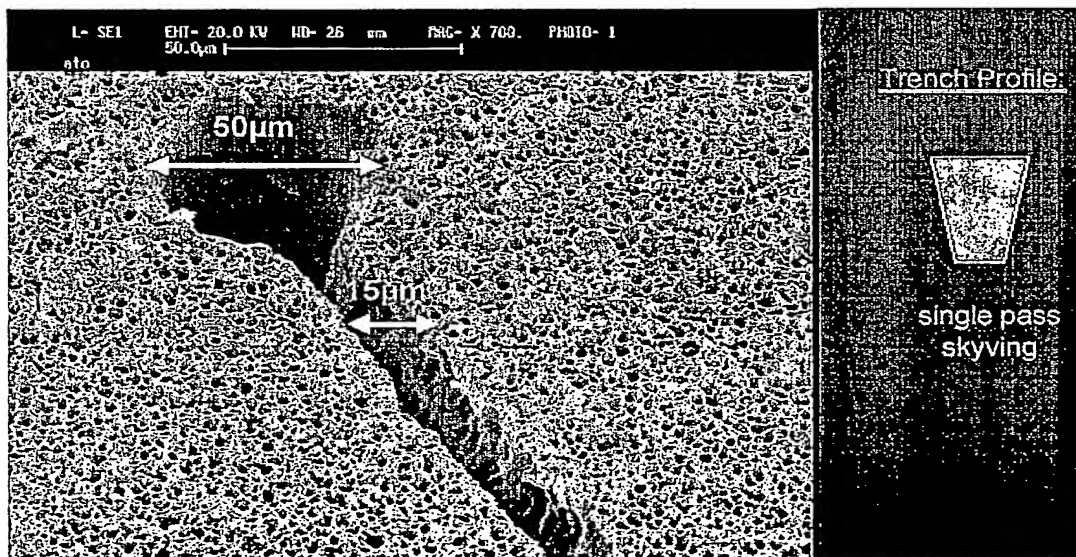
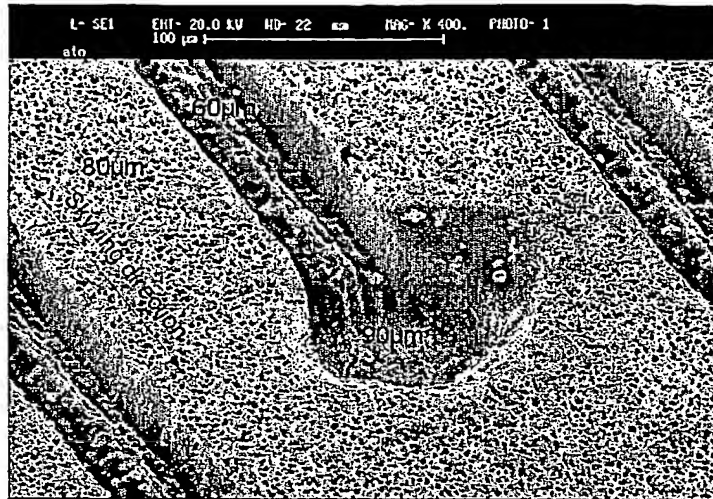
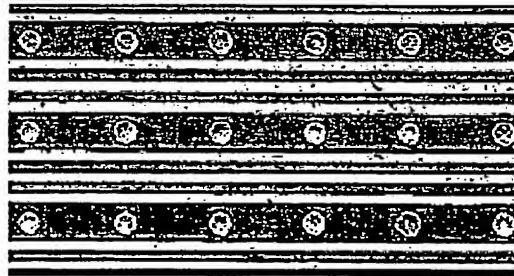


Fig. 12

**Via<sup>2</sup> - Process****Multi pass skiving – before laser polish - 0.8 mm BGA****SEM – Detail of hole trench intersection****Trench Profile****Multiple pass skyving****polished****Several different  
laser routines are  
possible.****Fig. 13****Fig. 14****BEST AVAILABLE COPY**

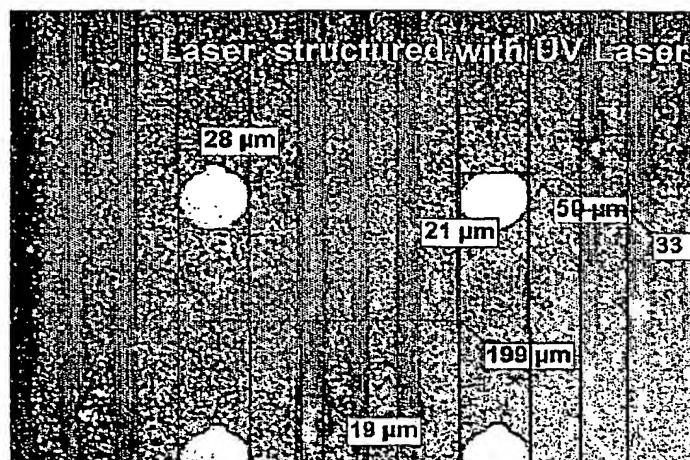


Fig. 15

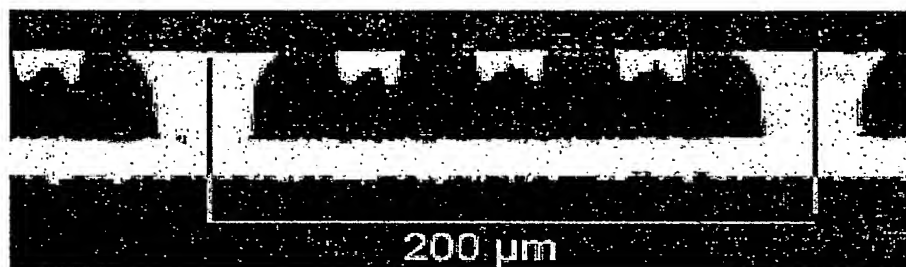


Fig. 16



Fig. 17



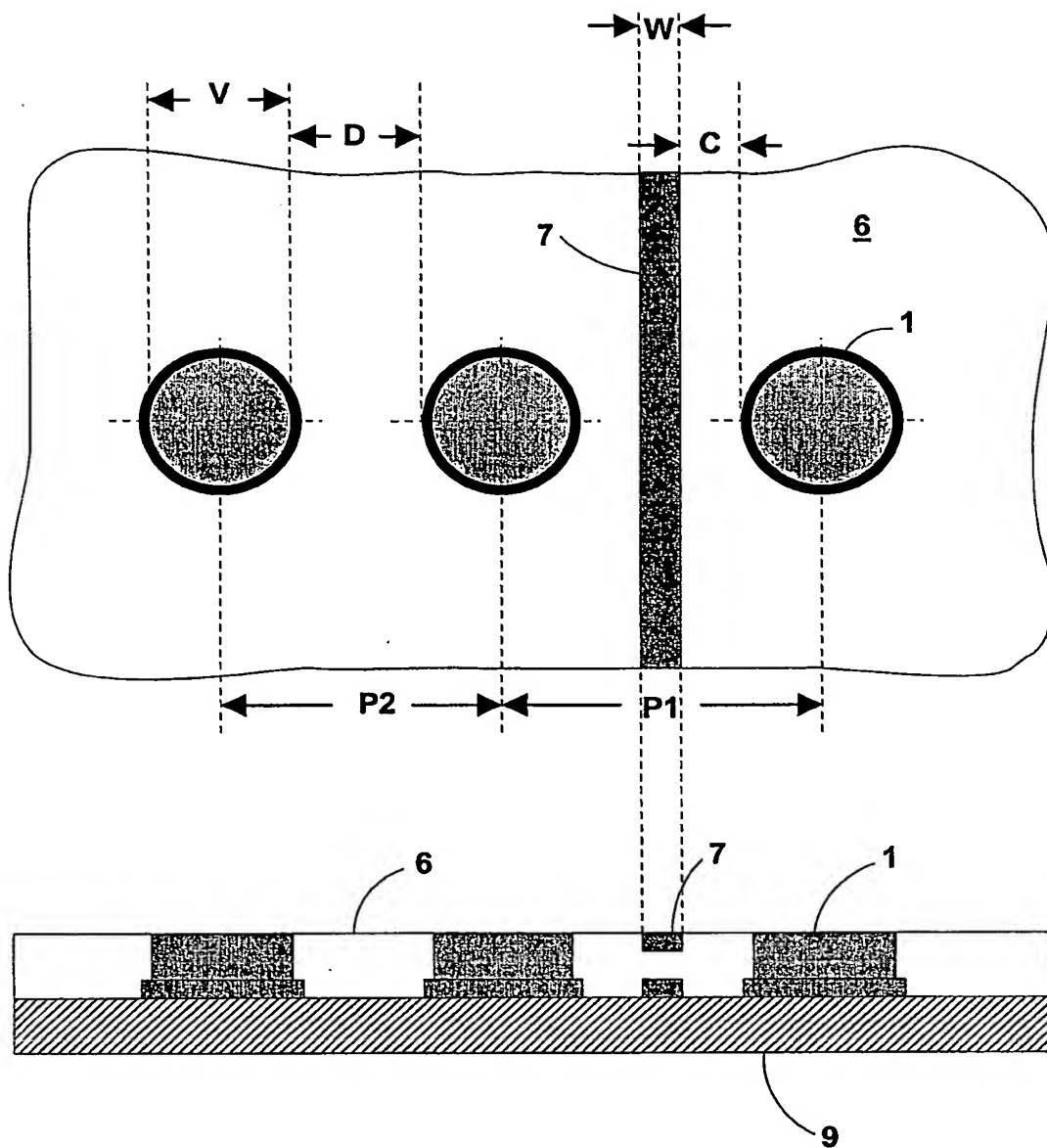


Fig. 18